SES22534-50 A/B

Shin-Etsu Silicones of America, Inc.
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Product Description

Shin-Etsu's SES22534-50 A/B is a dual component, room-temperature cure, self leveling potting encapsulent that cures to form a durable, flexible rubber to protect electronic components. SES22534-50 A/B exhibits excellent unprimed adhesion to most circuit board substrates, metals, plastics, glass, and ceramics.

Product Features

- Dual component
- 1:1 mix ratio
- Room-temperature cure
- Self-leveling
- Black Color

Typical Applications

- Protecting and electrically isolating electronic components
- Stress Reduction

Typical Properties

Type	Potting Encapsulant
Cure Type	Addition
One/Two Component	Two
Color	Black
Density @ 23C (g/cm^3)	0.98
Viscosity (cps)	570.00
Viscosity B (cps)	290.00
Mix Ratio by weight	100:100
Cure Conditions	24 hours @ 23 c
Snap Time (min)	24
Shore 00 Hardness	50
Usable Temperature Range (C)	-40C to +180C

Note: Values are not for specification purposes.

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